



















PCB Number: TIDA-00399 PCB LOGO PCB LOGO PCB Rev: E1 Texas Instruments Pb-Free Symbol Label Table Label Text 3p3V_Variant 3.3V VIN Bypass ADJ_Variant Adjustable VIN ZZ2

Assembly Note

These assemblies are ESD sensitive, ESD precautions shall be observed. ZZ3

Assembly Note

These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable. ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified. Orderable: N/A Designed for Public Release | Mod. Date: 3/19/2015 | TID #: SSD Power Delivery | Project Title: Titl TEXAS INSTRUMENTS http://www.ti.com © Texas Instruments 2014 5

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